

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.2)
LeadCount	44
Option	Pb-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	72.61	2.72 E-01	539459
Epoxy, Cresol Novolac	19.36	7.24 E-02	143836
Phenol Resin	4.84	1.81 E-02	35959
Antimony Trioxide	1.45	5.42 E-03	10773
Brominated Epoxy Resin	1.45	5.42 E-03	10773
Carbon Black	0.29	1.08 E-03	21551
Subtotal		3.74 E-01	742954

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	198865
Ni	3.00	3.12 E-03	6200
Si	0.65	6.73 E-04	1336
Mg	0.15	1.58 E-04	313
Subtotal		1.04 E-01	206714

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2046

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.18 E-03	12276

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	9.11 E-04	1810

Chip			
	% of Chip	Weight (g)	PPM
Si	100.0	1.49 E-02	29565

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	1.76 E-03	3496
Epoxy resin	18.9	4.40 E-04	874
Gamma Butyrolactone	2.8	6.60 E-05	131
Curing agent & hardener	2.8	6.60 E-05	131
Subtotal		2.33 E-03	4633

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321, ICP-OES
Cd	None Detected	Draft IEC 62321, ICP-OES
Hg	None Detected	Draft IEC 62321, ICP-OES
Cr+6	None Detected	Draft IEC 62321, UV-VIS
PBB	None Detected	Draft IEC 62321, GC-MS
PBDE	None Detected	Draft IEC 62321, GC-MS

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321, ICP-OES
Cd	None Detected	Draft IEC 62321, ICP-OES
Hg	None Detected	Draft IEC 62321, ICP-OES
Cr+6	None Detected	Draft IEC 62321, UV-VIS
PBB	None Detected	Draft IEC 62321, GC-MS
PBDE	None Detected	Draft IEC 62321, GC-MS

Package Totals	
Weight (g)	PPM
5.03 E-01	1000000

S-01

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ADI Proprietary

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.2)
LeadCount	44
Option	Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Silica	72.61	2.72 E-01	539459
Epoxy, Cresol Novolac	19.36	7.24 E-02	143836
Phenol Resin	4.84	1.81 E-02	35959
Antimony Trioxide	1.45	5.42 E-03	10773
Brominated Epoxy Resin	1.45	5.42 E-03	10773
Carbon Black	0.29	1.06 E-03	2155
Subtotal		3.74 E-01	742954

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	198865
Ni	3.00	3.12 E-03	6200
Si	0.65	6.73 E-04	1336
Mg	0.15	1.58 E-04	313
Subtotal		1.04 E-01	206714

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2046

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	5.25 E-03	10436
Pb	15	9.27 E-04	1842
Subtotal		6.18 E-03	12278

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	9.11 E-04	1810

Chip			
	% of Chip	Weight (g)	PPM
Si	100.0	1.49 E-02	29565

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	1.76 E-03	3496
Epoxy resin	18.9	4.40 E-04	874
Gamma Butyrolactone	2.8	6.60 E-05	131
Curing agent & hardener	2.8	6.60 E-05	131
Subtotal		2.33 E-03	4633

Package Totals		
Weight (g)	PPM	
5.03 E-01	1000000	

S-02

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ADI Proprietary

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.2)
LeadCount	44
Option	Pb-free, Halide-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.91	3.25 E-01	639326
Epoxy & Phenol Resin	12.78	4.78 E-02	94012
Carbon black	0.31	1.16 E-03	2280
Subtotal		3.74 E-01	735618

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	196895
Ni	3.00	3.12 E-03	6140
Si	0.65	6.76 E-04	1330
Mg	0.15	1.56 E-04	307
Subtotal		1.04 E-01	204673

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2026

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.15 E-03	12091

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.78 E-03	3493

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	1.85 E-02	36396

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	2.19 E-03	4304
Epoxy resin	18.9	5.47 E-04	1076
Gamma Butyrolactone	2.8	8.20 E-05	161
Curing agent & hardener	2.8	8.20 E-05	161
Subtotal		2.90 E-03	5702

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Package Totals	
Weight (g)	PPM
5.08 E-01	1000000

S-03

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ADI Proprietary

Materials Declaration

Package	MQFP
Body Size	10 X 10 x 2.0 (+3.2)
LeadCount	44
Option	with Pb, Halide-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.91	3.25 E-01	639326
Epoxy & Phenol Resin	12.78	4.78 E-02	94012
Carbon black	0.31	1.16 E-03	2280
Subtotal		3.74 E-01	735618

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	1.00 E-01	196895
Ni	3.00	3.12 E-03	6140
Si	0.65	6.76 E-04	1330
Mg	0.15	1.56 E-04	307
Subtotal		1.04 E-01	204673

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	1.03 E-03	2026

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	5.22 E-03	10278
Pb	15	9.22 E-04	1814
Subtotal		6.15 E-03	12091

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.78 E-03	3493

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	1.85 E-02	36396

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	75.5	2.19 E-03	4304
Epoxy resin	18.9	5.47 E-04	1076
Gamma Butyrolactone	2.8	8.20 E-05	161
Curing agent & hardener	2.8	8.20 E-05	161
Subtotal		2.90 E-03	5702

Package Totals	
Weight (g)	PPM
5.08 E-01	1000000

Molding Compound		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	Draft IEC 62321. ICP-OES
Cd	None Detected	Draft IEC 62321. ICP-OES
Hg	None Detected	Draft IEC 62321. ICP-OES
Cr+6	None Detected	Draft IEC 62321. UV-VIS.
PBB	None Detected	Draft IEC 62321. GC-MS.
PBDE	None Detected	Draft IEC 62321. GC-MS.

S-04

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ADI Proprietary